

## PACKAGE STRUCTURE AND POWER MODULE USING SAME

### ABSTRACT OF THE DISCLOSURE

A package structure includes a first insulation layer, a first re-distribution block, at least one electronic component, a second re-distribution block, a second insulation layer, a first heat spreader, a heat dissipation substrate, a second heat spreader and plural thermal conduction structures. A part of the second re-distribution block is disposed on a part of a top surface of the first insulation layer, and the other part of the second re-distribution block is located in the first insulation layer. At least one of the conducting terminals is connected with the second re-distribution block. At least one of the thermal conduction structures is connected with at least one of the first re-distribution block and the second re-distribution block, and the thermal conduction structures are respectively extended outwardly from the opposite sides of the first insulation layer to form pins.

Figure 1